



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SQFP 48-64 LEAD

Stress	Sample Size	Device Hr./Cyc	Condition	Total Fails	Fail Percentage
BOND INT	240	120,000	200°C +N2	0	0.00
HAST	530	53,000	130°C, 85%RH	0	0.00
Pressure Pot	730	70,080	121°, 15 PSIG	0	0.00
Solder DUNK	140	420	260°C, 10SEC	0	0.00
Solderability	180	1,440	883 M2003	0	0.00
Temp Cycle	930	305,000	-65°C-150°C	0	0.00